

AMENDMENTS TO THE CLAIMS:

Please amend claims 1, 6, 8, 12, 90, and 94, as indicated below. This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A heating apparatus for a coating film comprising:

a chamber having an inner space;

a heating plate ~~for heating~~ configured to heat a substrate to be processed, said heating plate having a support surface that supports the substrate to be processed with a coating film in said chamber;

a partition member arranged in said chamber so as to face the support surface, said partition member partitioning the inner space into first and second spaces and having a plurality of pores allowing the first and second spaces to connect with each other, the support surface being set in the first space, and the second space connected with an outside of said chamber through a first opening and a second opening formed in sides of said chamber; and

an air stream formation mechanism forming an air stream in the second space in order to discharge a substance evaporated from the coating film.
2. (Original) The apparatus according to claim 1, wherein said partition member is detachable from said heating apparatus.

3. (Original) The apparatus according to claim 1, wherein said partition member is formed from a material selected from the group consisting of a porous ceramic and a corrosion-resistant metal.

4. (Original) The apparatus according to claim 1, wherein said partition member has a pore diameter falling within a range of 2 μm to 100 μm .

5. (Previously Presented) The apparatus according to claim 1, wherein said air stream formation mechanism and at least condition selected from the group consisting of a pore diameter and porosity of said partition member are adjusted so as to discharge the evaporated substance into the second space via the plurality of pores of said partition member.

6. (Currently Amended) A heating apparatus for a coating film comprising:
a chamber having an inner space;
a heating plate ~~for heating~~ configured to heat a substrate to be processed, said heating plate having a support surface that supports the substrate to be processed with a coating film in said chamber; and

an adsorption plate arranged in said chamber so as to face the support surface, a surface of the adsorption plate which faces the substrate to be processed adsorbing a substance evaporated from the coating film.

7. (Original) The apparatus according to claim 6, wherein said adsorption plate is formed from a material selected from the group consisting of an oxide, a nitride, a material with

an oxide surface facing the substrate to be processed, and a material with a nitride surface facing the substrate to be processed.

8. (Currently Amended) The apparatus according to claim 6, wherein said adsorption plate comprises a temperature control function ~~for controlling~~ configured to control a temperature of said adsorption plate.

9. (Original) The apparatus according to claim 8, wherein said temperature control function sets the temperature of said adsorption plate to be higher than a temperature of said substrate to be processed.

10. (Original) The apparatus according to claim 8, wherein said temperature control function sets the temperature of said adsorption plate to be lower than a temperature of said substrate to be processed.

11. (Original) The apparatus according to claim 8, wherein said adsorption plate is formed from a material selected from the group consisting of an oxide, a nitride, a material with an oxide surface facing said substrate to be processed, and a material with a nitride surface facing said substrate to be processed.

12. (Currently Amended) The apparatus according to claim 6, wherein said adsorption plate is formed from a metal member, and

said apparatus further comprises a voltage generator ~~for generating~~ configured to generate an electric field between said heating plate and said metal member.

13. (Original) The apparatus according to claim 12, wherein said metal member receives a voltage lower than said heating plate from said voltage generator, and adsorbs said evaporated substance.

14. (Original) The apparatus according to claim 12, wherein said metal member receives a voltage higher than said heating plate from said voltage generator, and suppresses generation of said evaporated substance.

15-85. (Cancelled)

86. (Previously Presented) The apparatus according to claim 1, wherein the second space is positioned above the first space.

87. (Previously Presented) The apparatus according to claim 1, wherein the air stream contains the substance.

88. (Previously Presented) The apparatus according to claim 1, wherein the first opening is formed in a first side surface of the chamber and the second opening is formed in a second side surface of the chamber opposite the first side surface.

89. (Previously Presented) The apparatus according to claim 6, wherein the adsorption plate is positioned above the support surface.

90. (Currently Amended) A heating apparatus for a coating film comprising:
a chamber having an inner space;
a heating plate ~~for heating~~ configured to heat a substrate to be processed, said heating plate having a support surface that supports the substrate to be processed with a coating film in said chamber; and
an adsorption plate arranged in said chamber so as to face the support surface, said adsorption plate adsorbing a substance evaporated from the coating film, and said adsorption plate including a temperature control function for controlling a temperature of said adsorption plate.

91. (Previously Presented) The apparatus according to claim 90, wherein said temperature control function sets the temperature of said adsorption plate to be higher than a temperature of said substrate to be processed.

92. (Previously Presented) The apparatus according to claim 90, wherein said temperature control function sets the temperature of said adsorption plate to be lower than a temperature of said substrate to be processed.

93. (Previously Presented) The apparatus according to claim 90, wherein said adsorption plate is formed from a material selected from the group consisting of an oxide, a nitride, a

material with an oxide surface facing said substrate to be processed, and a material with a nitride surface facing said substrate to be processed.

94. (Currently Amended) A heating apparatus for a coating film comprising:

- a chamber having an inner space;
- a heating plate ~~for heating~~ configured to heat a substrate to be processed, said heating plate having a support surface that supports the substrate to be processed with a coating film in said chamber;
- an adsorption plate formed from a metal member and arranged in said chamber so as to face the support surface, said adsorption plate adsorbing a substance evaporated from the coating film; and
- a voltage generator for generating an electric field between said heating plate and said metal member.

95. (Previously Presented) The apparatus according to claim 94, wherein said metal member receives a voltage lower than said heating plate from said voltage generator, and adsorbs said evaporated substance.

96. (Previously Presented) The apparatus according to claim 94, wherein said metal member receives a voltage higher than said heating plate from said voltage generator, and suppresses generation of said evaporated substance.